

Amendments To the Claims

Claim 1 (Currently amended): A surface mount flipchip capacitor comprising:  
a wire having opposite first and second end surfaces and upper and lower face surfaces;  
a conductive powder element electrically connected to the wire and covering a portion of the wire  
upper face surface;  
the wire lower face surface being free from the conductive powder element;  
insulative material surrounding at least a portion of the conductive powder element and a portion  
of the wire upper face surface;  
a first terminal formed by a first body of conductive material disposed to the first end surface of  
the wire and a portion of the insulating material; and  
a second terminal formed by a second body of conductive material disposed over and being  
electrically connected to the upper end of the conductive powder element.

Claim 2 (Original): The surface mount flipchip capacitor of claim 1 wherein the first terminal  
is an anode end and the second terminal is a cathode end.

Claim 3 (Original): The surface mount flipchip capacitor of claim 1 wherein the conductive  
powder element is made of powder.

Claim 4 (Original): The surface mount flipchip capacitor of claim 3 wherein the powder is  
from the group consisting of: Ta, Nb, Hf, Zr, Ti, V, W, Be, and Al.

Claim 5 (Original): The surface mount flipchip capacitor of claim 3 wherein the powder is a  
substrate of a metal from the group consisting of: Ta, Nb, Hf, Zr, Ti, V, W, Be, and Al.

Claim 6 (Original): The surface mount flipchip capacitor of claim 3 wherein the powder has  
been electrophoretically deposited upon the wire.

Claim 7 (Original): The surface mount flipchip capacitor of claim 1 wherein the conductive  
powder element has a density between 3-8 g/cc.

Claim 8 (Original): The surface mount flipchip capacitor of claim 1 wherein the conductive powder element has a capacitance-voltage between 10 CV and 150 KCV.

Claim 9 (Original): The surface mount flipchip capacitor of claim 1 wherein the wire is a parallelepiped.

Claims 10-18 (Cancelled)

Claim 19 (Currently amended): A surface mount flipchip capacitor comprising:  
a wire having opposite first and second end surfaces and upper and lower face surfaces;  
a conductive powder element upon the wire covering a portion of only the upper face surface, the conductive powder element having a cathode end, an anode end, and conductive powder element sides extending between the anode and cathode ends;  
a layer of insulation material exterior of, and in covering relation over the cathode end and the conductive powder element sides, whereby the wire extends below and has a protruding wire portion extending beyond an exterior surface of the layer of insulation material;  
an anode layer of conductive material over the wire first end and a portion of the exterior surface of the insulation material so that the anode layer of conductive material is in electrical contact with the wire first end, whereby electrical continuity is achieved from the anode end of the conductive powder element, through the wire to the anode layer of conductive material;  
a cathode layer of conductive material over at least a portion of the cathode end of the conductive powder element approximately level with the anode layer of conductive material and in electrical contact with, the cathode end of the conductive powder element.

Claim 20 (Previously presented): The surface mount flipchip capacitor of claim 19 wherein the conductive powder element is made of electrophoretically deposited powder.

Claim 21 (Previously presented): The surface mount flipchip capacitor of claim 20 wherein the powder is from the group consisting of: Ta, Nb, Hf, Zr, Ti, V, W, Be, and Al.

Claim 22 (Previously presented): The surface mount flipchip capacity of claim 20 wherein the powder is a substrate of a metal from the group consisting of: Ta, Nb, Hf, Zr, Ti, V, W, Be, and Al.

Claim 23 (Previously presented): The surface mount flipchip capacitor of claim 19 wherein the conductive powder element has a density between 3-8 g/cc.

Claim 24 (Previously presented): The surface mount flipchip capacitor of claim 19 wherein the conductive powder element has a capacitance-voltage between 10 CV and 150 KCV,

Claim 25 (Previously presented): The surface mount flipchip capacitor of claim 19 wherein the wire is a parallelepiped.

Claim 26 (Previously presented): The surface mount flipchip capacitor of claim 19 wherein the wire is a foil sheet portion.

Claims 27-32 (Cancelled)

Claim 33 (New): The surface mount flipchip capacitor of claim 1 wherein the wire lower face surface is uncovered.

Claim 34 (New): The surface mount flipchip capacitor of claim 19 wherein the wire lower face surface is free from the conductive powder element.

Claim 35 (New): The surface mount flipchip capacitor of claim 19 wherein the wire lower face surface is uncovered.